

Customer Information Notification

10-Jan-2020 Issue Date: Effective Date: 11-Jan-2020 Dear Emma Tempest,

Here's your personalized quality information concerning products Premier Farnell PLC purchased from NXP. For detailed information we invite you to view this notification online

This notice is NXP Company Proprietary.

201912006



$QUALI^{-}$

[] Test

[]Test

Process

[]Test

Packing/Shipping/Labeling Equipment spec./Test

Location

[] Design

[X] Errata

coverage

[X] Electrical

Change Category

[] Wafer Fab Process

[] Wafer Fab Materials

[] Wafer Fab Location

[] Firmware

[] Other

Process

Materials

Location

[] Assembly []

i.MXRT1064 Data Sheet Rev 1 and Errata Rev 1.1 Updates

Description

NXP Semiconductors announces errata update to revision 1.1 and data sheet update to revision 1 for i.MXRT1064. The revision history included in the updated documents provides a detailed description of the changes. Changes are summarized below.

[] Assembly [] Product Marking

Specification

[] Assembly [] Mechanical

For RT1064 Chip Errata:

Added following errata:

ERR050235 CCM: Incorrect clock setting for CAN affects UART clock gating

For RT1064 Consumer DS, Data Sheet Changes:

1. Updated ADC and SPI NAND Flash in the Section 1.1, Features; removed DAC from Section

1.1, Features

2. Updated ADC and RAM in the Figure 2, "i.MX RT1064 system block diagram"

3. Updated the RT website link in the Section 1.2, Ordering information

4. Updated FlexSPI and SNVS in the Table 1, Ordering information; added KPP, SPI, XBAR/AOI, CSU, and second package information in the Table 1, Ordering information

5. Removed tamper detection from the Table 2, i.MX RT1064 modules list

6. Updated the on-chip termination values of JTAG TCK and JTAG MOD in the Table 4, JTAG Controller

interface summary

7. Updated the Section 4.1.2, Thermal resistance

8. Changed 528 MHz PLL to System PLL in the Table 16, System PLL's electrical parameters

9. Changed 480 MHz PLL to USB PLL in the Table 18, USB PLL's electrical parameters

10.Updated the VDD name of supply voltage conditions column in the Table 54, 12-bit ADC operating conditions

11.Updated the Section 4.9.1, LPSPI timing parameters

12.Updated the Table 82, Boot through UART1 and removed the Table, Boot through UART2

13.Updated the Figure 53, "10 x 10 mm BGA, case x package top, bottom, and side Views"

14.Added the Section 7.2, 12 x 12 mm package information

For RT1064 Industrial DS, Data Sheet Changes:

1. Updated SPI NAND Flash in the Section 1.1, Features

2. Updated FlexSPI, LCD/CSI/PXP, and SNVS in the Table 1, Ordering information; added KPP, SPI,

XBAR/AOI, and CSU in the Table 1, Ordering information

3. Updated RAM in the Figure 2, "i.MX RT1064 system block diagram"

4. Updated the Section 4.1.2, Thermal resistance

5. Updated the Table 82, Boot through UART1 and removed the Table, Boot through UART2

6. Updated the Figure 53, "10 x 10 mm BGA, case x package top, bottom, and side Views" and Figure 54,

"12 x 12 mm BGA, case x package top, bottom, and side Views"

The i.MXRT1064 errata revision 1.1 is attached to this notice, and can be found at: https://www.nxp.com/products/processors-and-microcontrollers/arm-microcontrollers/i.mx-rt-series/i.mxrt1064-crossover-processor-with-arm-cortex-m7-core:i.MX-RT1064?tab=Documentation_Tab&linkline=Errata

The i.MXRT1064 data sheet revision 1 is attached to this notice, and can be found at:

https://www.nxp.com/products/processors-and-microcontrollers/arm-microcontrollers/i.mx-rt-series/i.mxrt1064-crossover-processor-with-arm-cortex-m7-core:i.MX-

RT1064?tab=Documentation_Tab&linkline=Data-Sheet

Reason

The errata was added for additional technical clarification on some device features.

The data sheets have been updated to correct errors and / or provide additional technical clarification on some device features.

Identification of Affected Products

Product identification does not change

Anticipated Impact on Form, Fit, Function, Reliability or Quality

No impact on form, fit, function, reliability or quality.

Data Sheet Revision

A new datasheet will be issued

Additional information

Affected products and sales history information: see attached file

Additional documents: view online

Contact and Support

For all inquiries regarding the ePCN tool application or access issues, please <u>contact NXP "Global Quality</u> <u>Support Team"</u>.

For all Quality Notification content inquiries, please contact your local NXP Sales Support team.

For specific questions on this notice or the products affected please contact our specialist directly:

NameWayne WangPositionSYSTEMS & APPLICATIONS ENGINEERe-mail addresswayne.wang@nxp.com

At NXP Semiconductors we are constantly striving to improve our product and processes to ensure they reach the highest possible Quality Standards. Customer Focus, Passion to Win.

NXP Quality Management Team.

About NXP Semiconductors

NXP Semiconductors N.V. (NASDAQ: NXPI) provides High Performance Mixed Signal and Standard Product solutions that leverage its leading RF, Analog, Power Management, Interface, Security and Digital Processing expertise. These innovations are used in a wide range of automotive, identification, wireless infrastructure, lighting, industrial, mobile, consumer and computing applications.

You have received this email because you are a designated contact or subscribed to NXP Quality Notifications. NXP shall not be held liable if this Notification is not correctly distributed within your organization.

This message has been automatically distributed. Please do not reply.

View Notification	Subscription	<u>Support</u>
NXP Privacy Policy Terms of Use		

NXP Semiconductors High Tech Campus, 5656 AG Eindhoven, The Netherlands © 2006-2010 NXP Semiconductors. All rights reserved.